

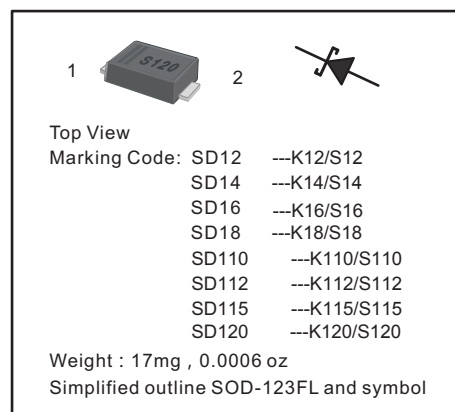
Surface Mount Schottky Barrier Rectifier
Reverse Voltage -20 to 200V
Forward Current - 1.0 A

Features

- Metal silicon junction, majority carrier conduction
- For surface mounted applications
- Low power loss, high efficiency
- High forward surge current capability
- For use in low voltage, high frequency inverters, free wheeling, and polarity protection applications

PINNING

PIN	DESCRIPTION
1	Cathode
2	Anode



Absolute Maximum Ratings and Electrical characteristics

Ratings at 25 °C ambient temperature unless otherwise specified. Single phase, half wave, 60Hz resistive or inductive load, for capacitive load, derate by 20 %

Parameter	Symbols	SD12X	SD14X	SD16X	SD18X	SD110X	SD112X	SD115X	SD120X	Units
Maximum Repetitive Peak Reverse Voltage	V _{RRM}	20	40	60	80	100	120	150	200	V
Maximum RMS voltage	V _{RMS}	14	28	42	56	70	84	105	140	V
Maximum DC Blocking Voltage	V _{DC}	20	40	60	80	100	120	150	200	V
Maximum Average Forward Rectified Current	I _{F(AV)}	1.0								A
Peak Forward Surge Current, 8.3ms Single Half Sine-wave Superimposed on Rated Load (JEDEC method)	I _{FSM}	40				30				A
Max Instantaneous Forward Voltage at 1 A	V _F	0.55		0.70		0.85		0.90		V
Maximum DC Reverse Current T _a = 25°C at Rated DC Reverse Voltage T _a =100°C	I _R	0.3 10				0.2 5		0.1 2		mA
Typical Junction Capacitance ¹⁾	C _j	110		80						pF
Typical Thermal Resistance ²⁾	R _{θJA}	115								°C/W
Operating Junction Temperature Range	T _j	-55 ~ +125								°C
Storage Temperature Range	T _{stg}	-55 ~ +150								°C

1) Measured at 1MHz and applied reverse voltage of 4 V D.C.

2) P.C.B. mounted with 0.2 X 0.2" (5 X 5 mm) copper pad areas.



Fig.1 Forward Current Derating Curve

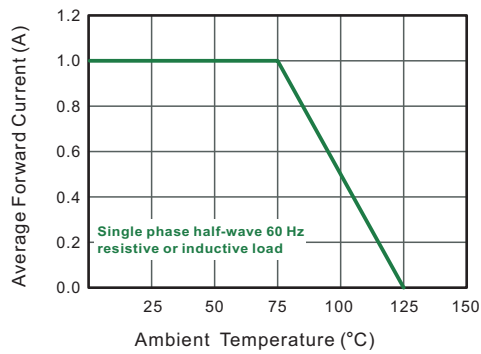


Fig.2 Typical Reverse Characteristics

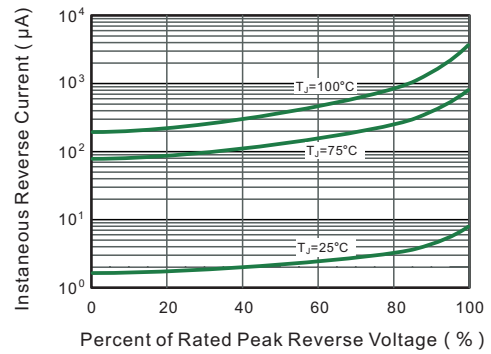


Fig.3 Typical Forward Characteristic

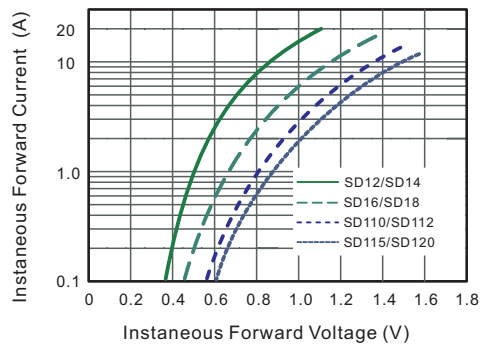


Fig.4 Typical Junction Capacitance

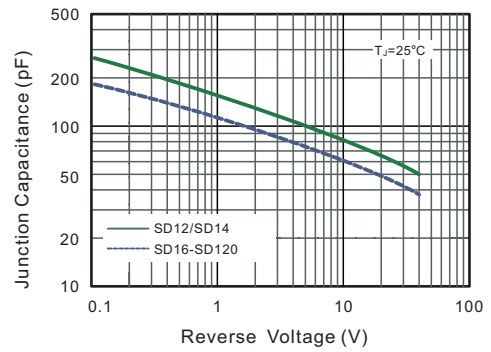


Fig.5 Maximum Non-Repetitive Peak Forward Surge Current

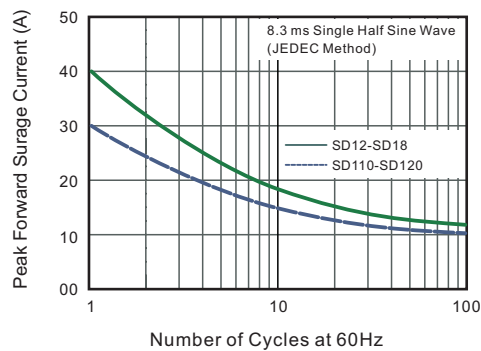
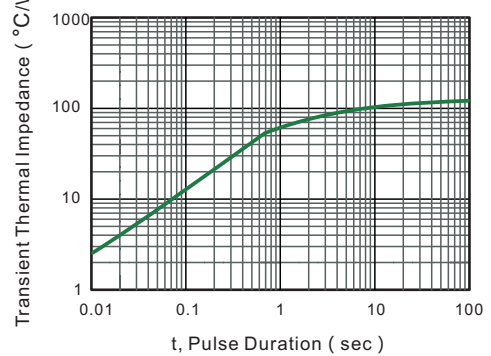


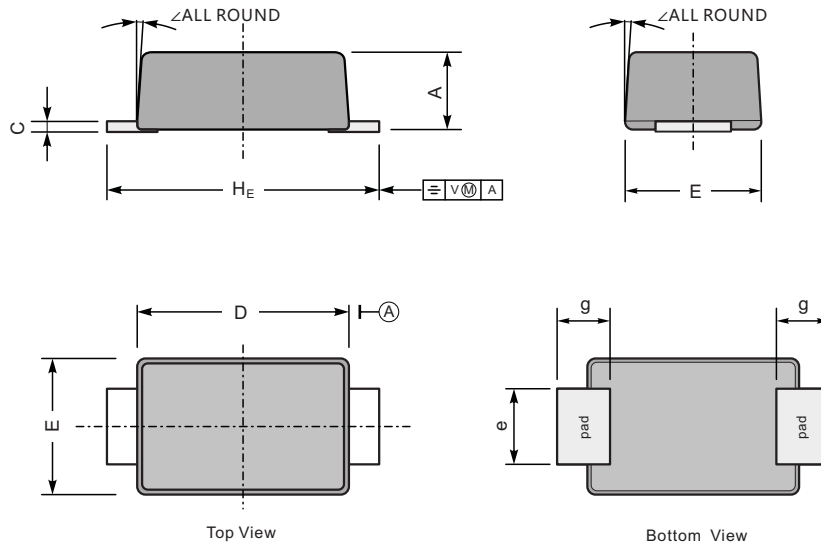
Fig.6- Typical Transient Thermal Impedance



PACKAGE OUTLINE

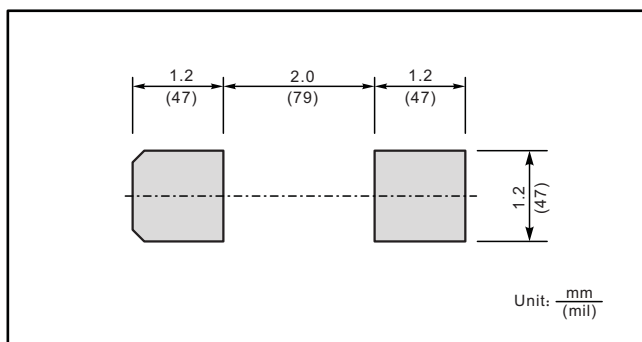
Plastic surface mounted package; 2 leads

SOD123FL



UNIT		A	C	D	E	e	g	H _E	∠
mm	max	1.1	0.20	2.9	1.9	1.1	0.9	3.8	7°
	min	0.9	0.12	2.6	1.7	0.8	0.7	3.5	
mil	max	43	7.9	114	75	43	35	150	
	min	35	4.7	102	67	31	28	138	

The recommended mounting pad size

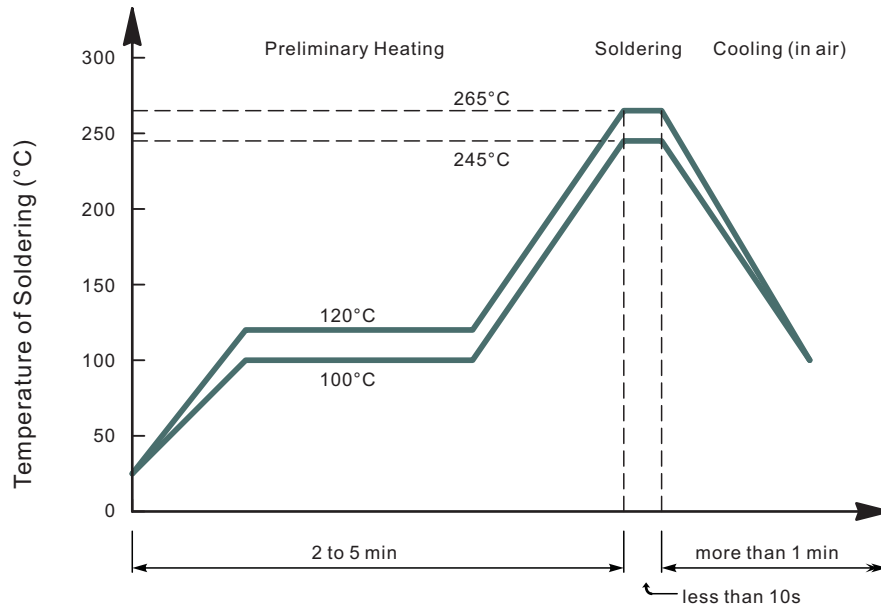


Marking

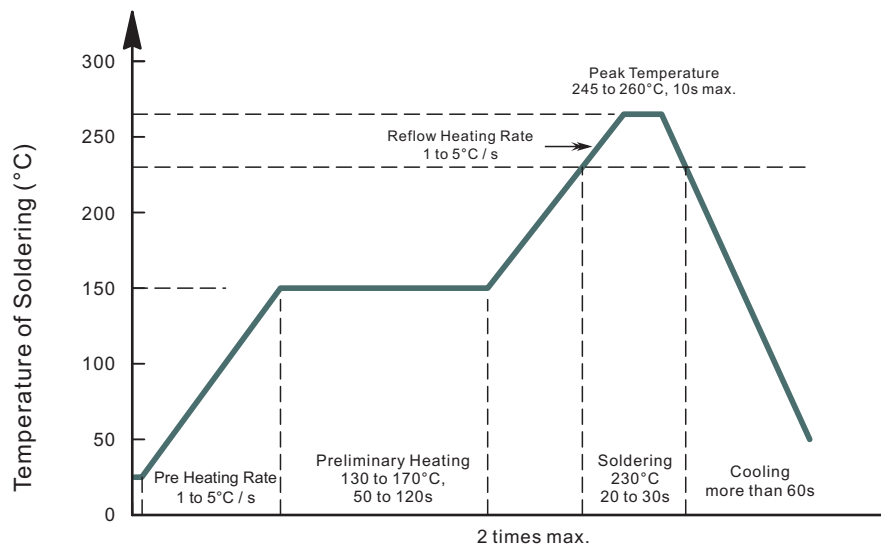
Type number	Marking code
SD12X	K12/S12
SD14X	K14/S14
SD16X	K16/S16
SD18X	K18/S18
SD110X	K110/S110
SD112X	K112/S112
SD115X	K115/S115
SD120X	K120/S120



• Recommended condition of flow soldering



• Recommended condition of reflow soldering



Recommended peak temperature is over 245 °C. If peak temperature is below 245 °C, you may adjust the following parameters; time length of peak temperature (longer), time length of soldering (longer), thickness of solder paste (thicker)

• Condition of hand soldering

Temperature: 350°C

Time: 3s max.

Times: one time

• Remark:

Lead free solder paste (96.5Sn/3.0Ag/0.5Cu)